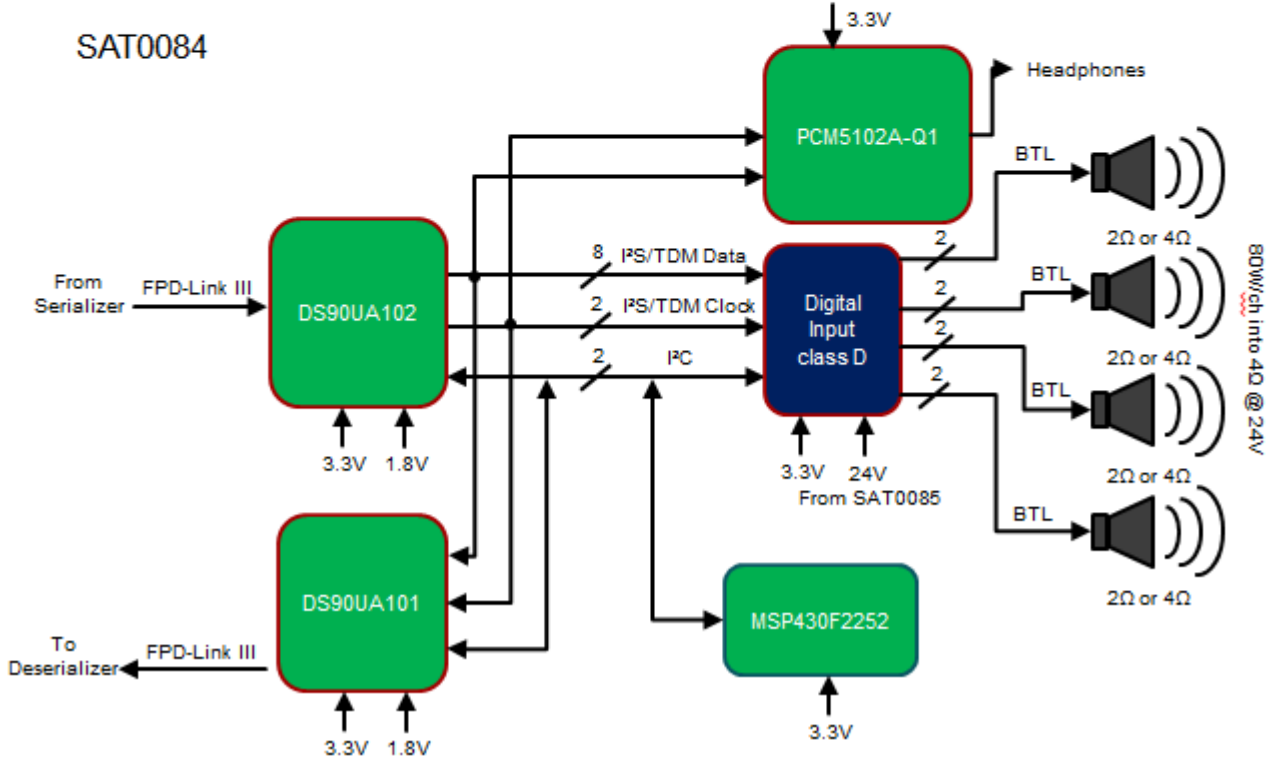


SAT0084



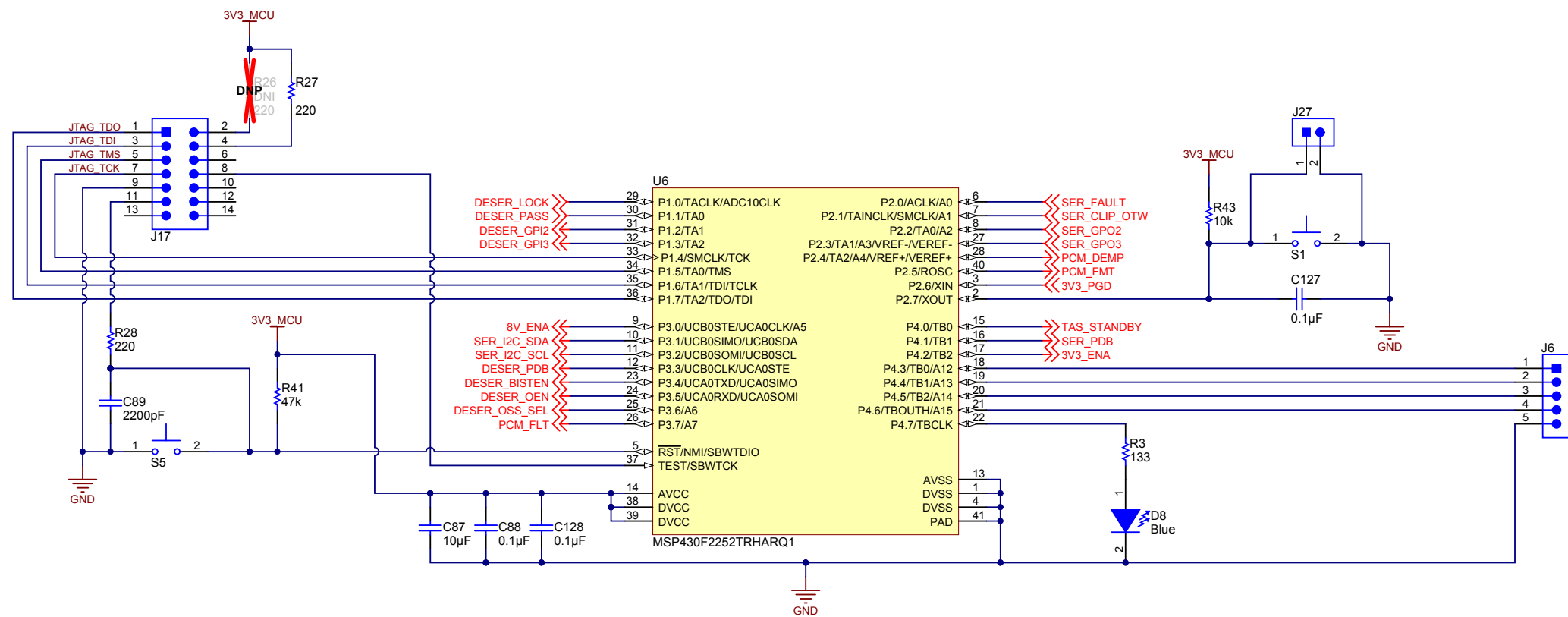
Revision History	
Revision	Notes
E1	Initial release



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TIDA-00223		Designed for: Public Release	Mod. Date: 7/10/2014
Number: SAT0084		Rev: E1.1	Project Title: FPD-Link III Class-D Amplifier
SVN Rev: Not in version control		Sheet Title: Cover	
Drawn By: Viktor Schneigelberger		Assembly Variant: COAX	Sheet: 1 of 7
Engineer: Viktor Schneigelberger		File: SAT0084E1-1_Cover.SchDoc	Size: B
		Contact: http://www.ti.com/support	

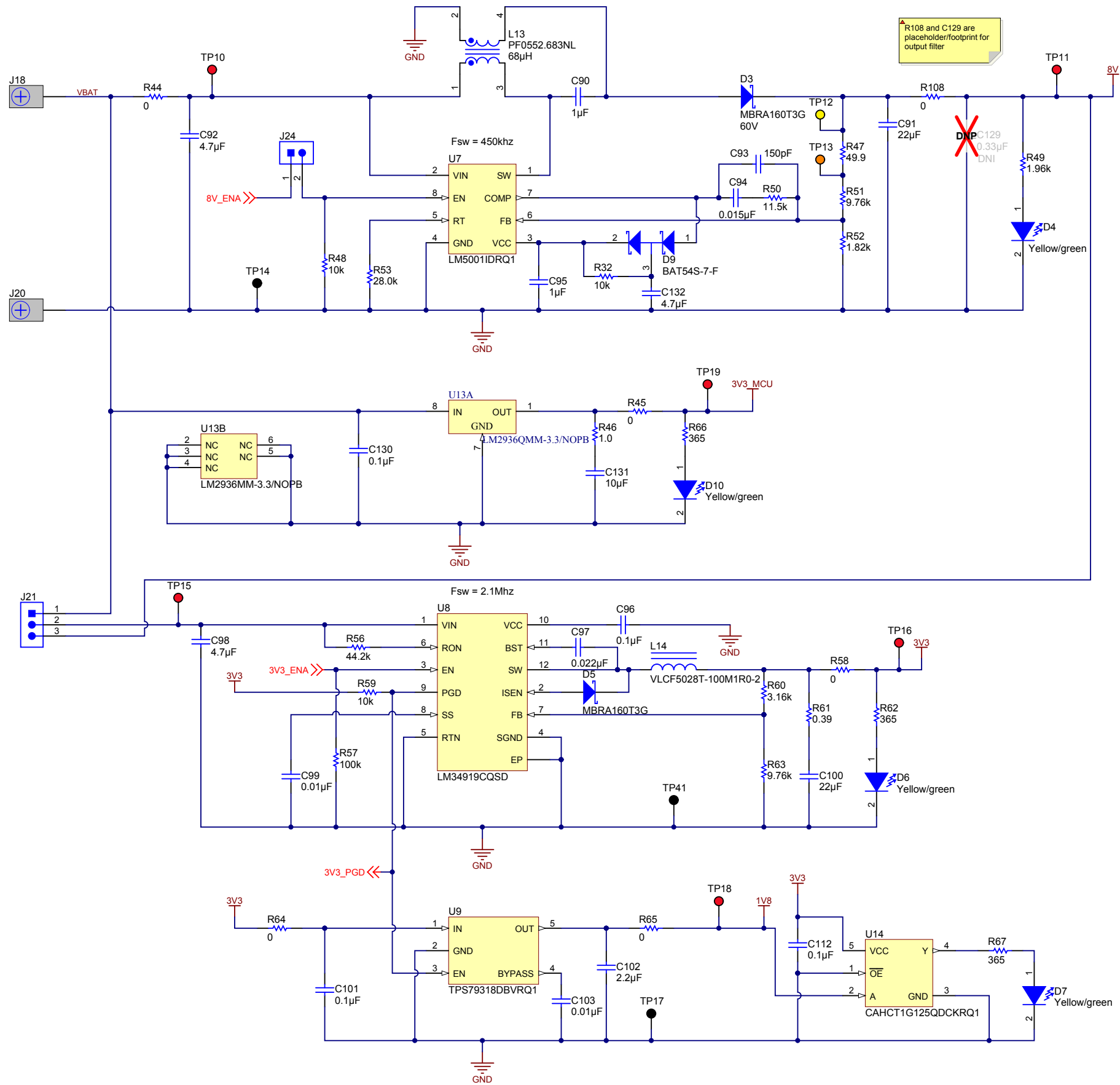




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TIDA-00223		Designed for: Public Release		Mod. Date: 7/10/2014	
Project Title: FPD-Link III Class-D Amplifier		SVN Rev: Not in version control		Rev: E1.1	
Number: SAT0084		Rev: E1.1		Sheet Title: MSP430	
Drawn By: Viktor Schneigelberger		Assembly Variant: COAX		Sheet: 2 of 7	
Engineer: Viktor Schneigelberger		File: SAT0084E1-1_MCU_SchDoc		Size: B	
		Contact: http://www.ti.com/support			



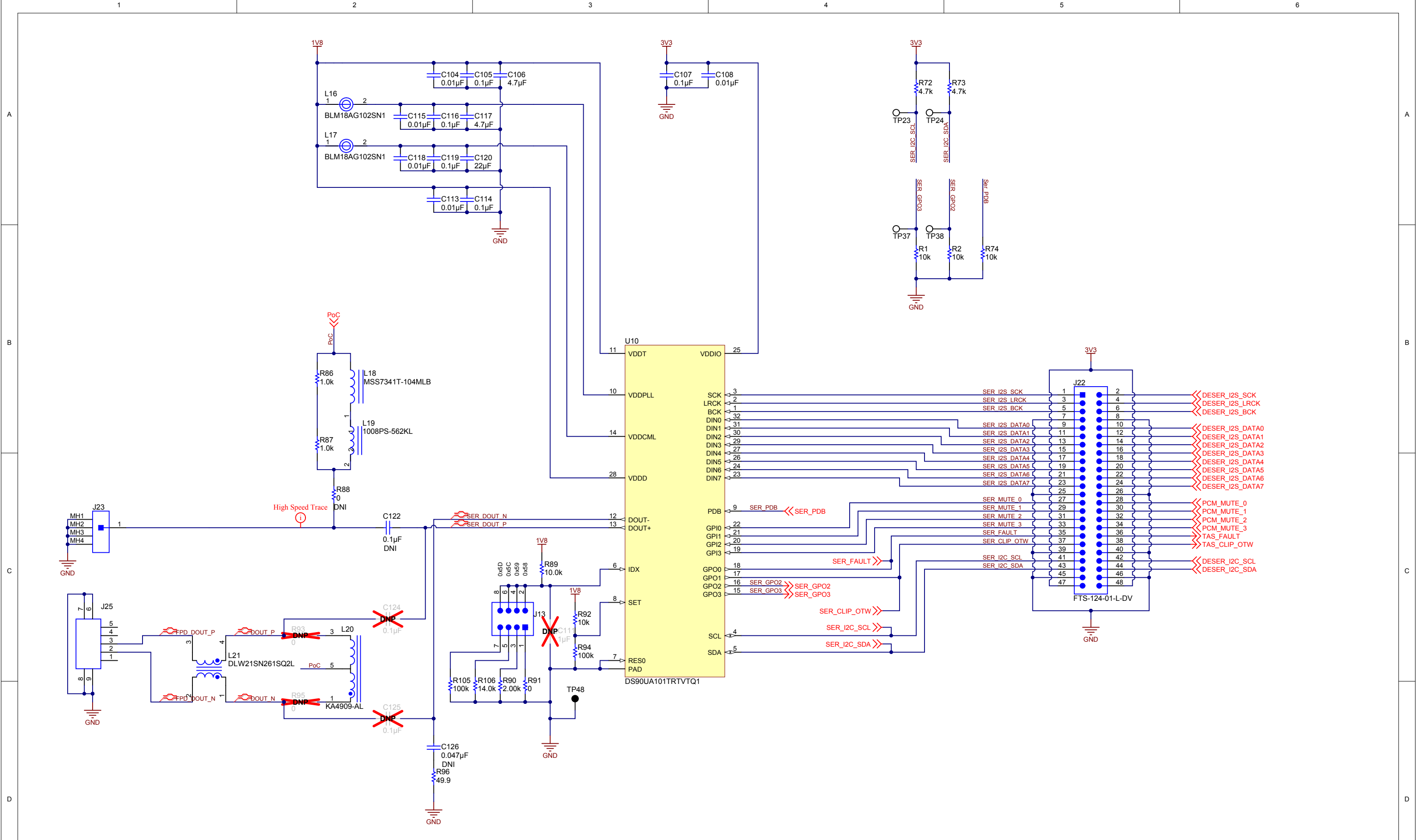


R108 and C129 are placeholder/footprint for output filter

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TIDA-00223		Designed for: Public Release	Mod. Date: 6/30/2014
Project Title: FPD-Link III Class-D Amplifier		Number: SAT0084	Rev: E1.1
Sheet Title: Power supply		Not in version control	
Assembly Variant: COAX		Sheet: 3 of 7	
File: SAT0084E1-1 Power_SchDoc		Size: B	
Contact: http://www.ti.com/support		Engineer: Viktor Schneigelberger	



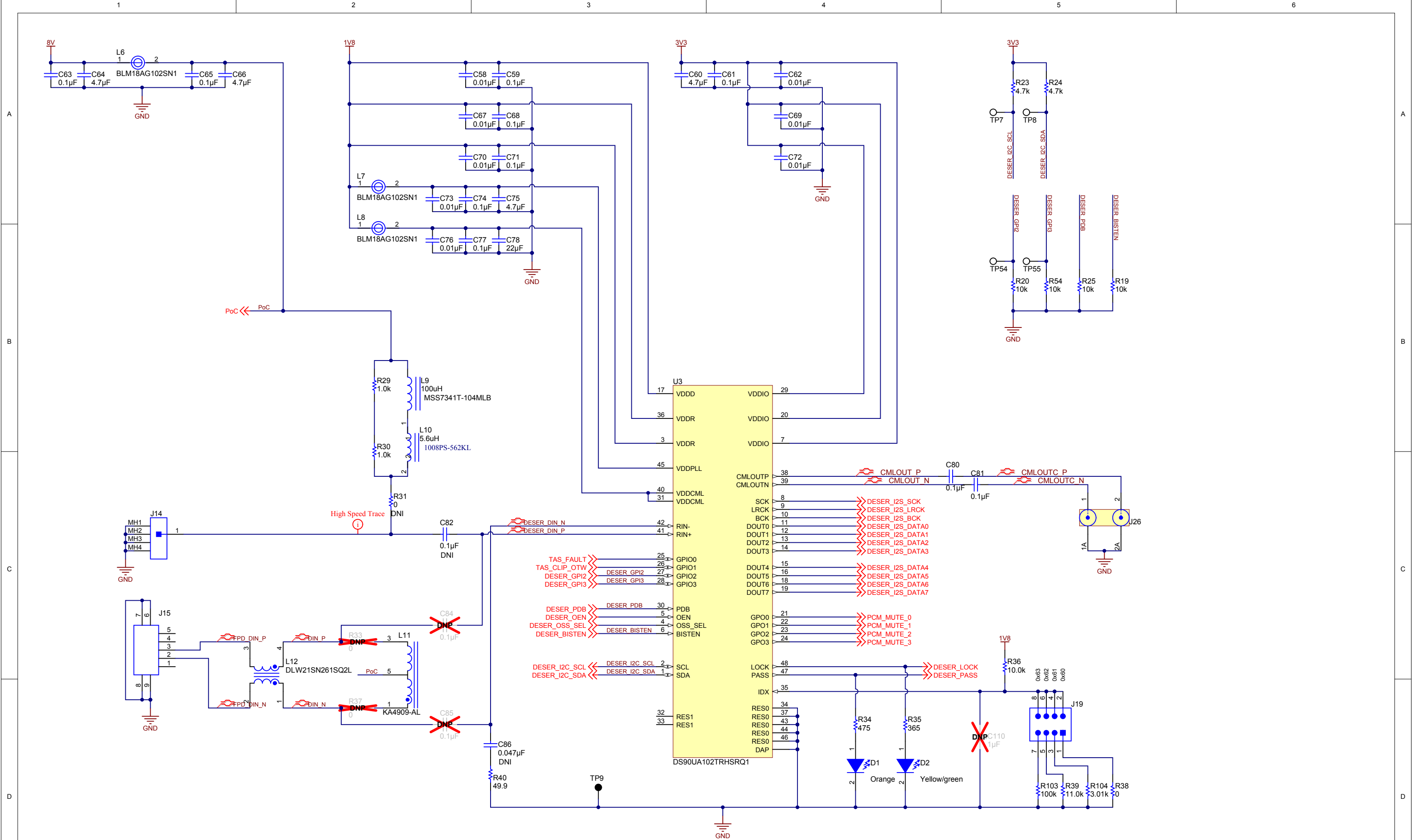


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TIDA-00223		Designed for: Public Release		Mod. Date: 7/10/2014	
Project Title: FPD-Link III Class-D Amplifier		Sheet Title: Serializer		Sheet: 4 of 7	
Number: SAT0084		Rev: E1.1		File: SAT0084E1-1_Ser.SchDoc	
SVN Rev: Not in version control		Assembly Variant: COAX		Size: B	
Drawn By: Viktor Schneigelberger		Engineer: Viktor Schneigelberger		Contact: http://www.ti.com/support	



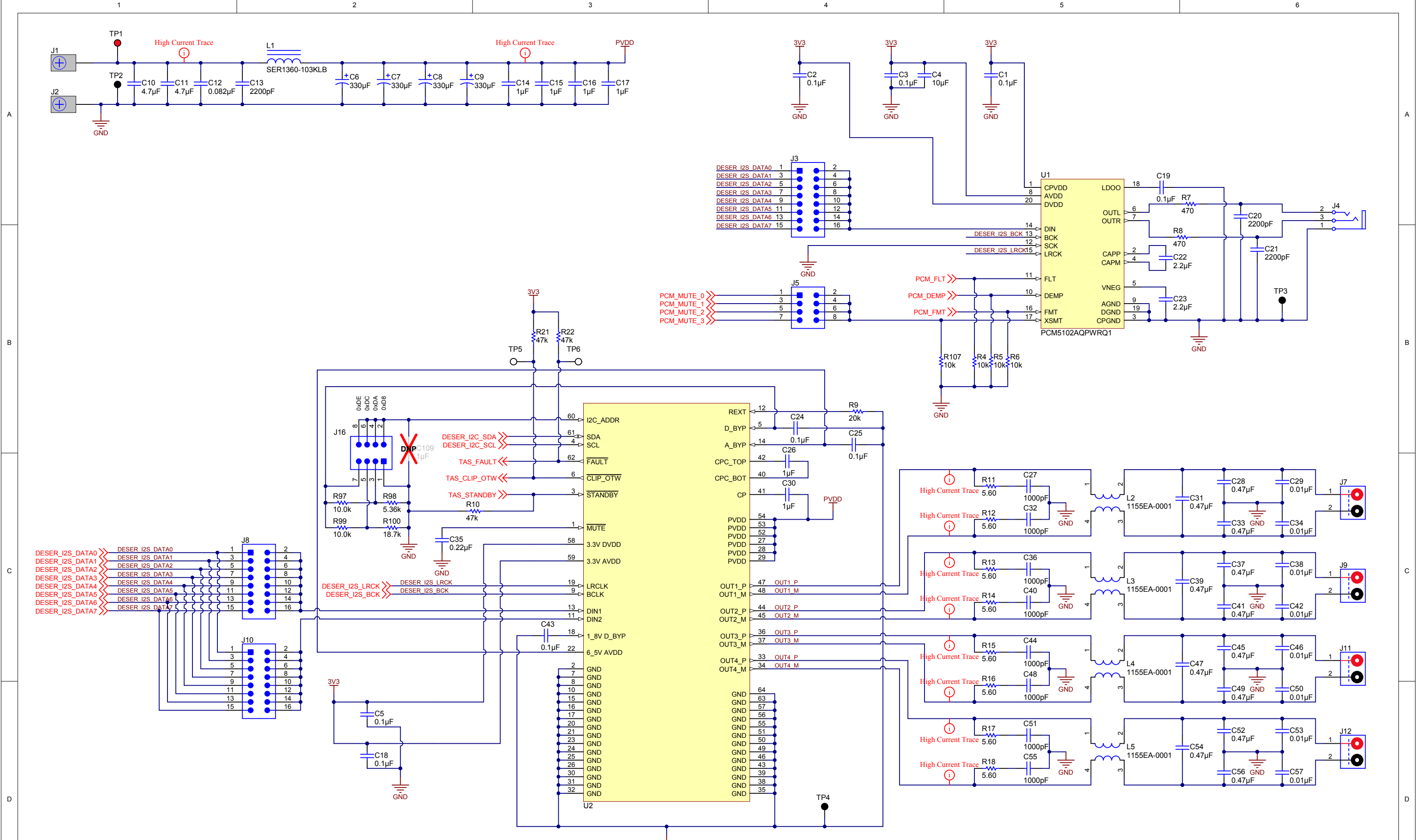
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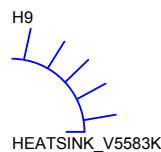
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TIDA-00223		Designed for: Public Release		Mod. Date: 7/10/2014	
Number: SAT0084		Rev: E1.1		Project Title: FPD-Link III Class-D Amplifier	
SVN Rev: Not in version control		Assembly Variant: COAX		Sheet Title: Deserializer	
Drawn By: Viktor Schneigelberger		File: SAT0084E1-1_DeSer_SchDoc		Sheet 5 of 7	
Engineer: Viktor Schneigelberger		Contact: http://www.ti.com/support		Size: B	



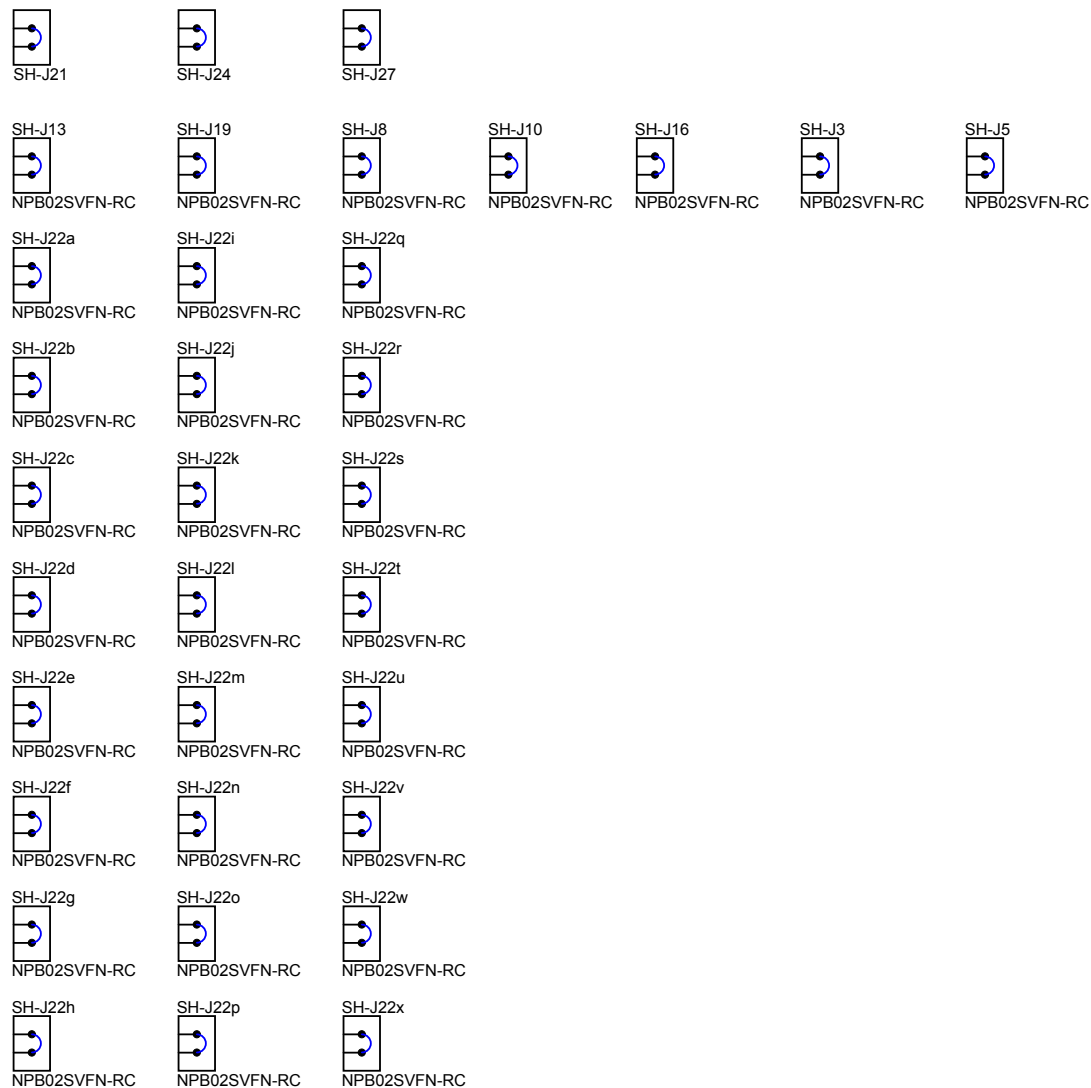


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PCB Number: SAT0084
PCB Rev: E1.1

PCB LOGO
Texas Instruments



H18
MECH
Any available

LBL1
PCB Label
Size: 0.65" x 0.20"

ZZ1
Label Assembly Note
This Assembly Note is for PCB labels only

ZZ2
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

ZZ5
Assembly Note
Apply a thin layer of heatsink grease on top of U2 before installing heatsink

ZZ6
Assembly Note
When installing J7, J8, J11, and J12, do not install the bottom-side insulator. Nuts must contact bottom copper pads.

ZZ7
Assembly Note
When installing J1, J2, J18, and J20, solder AND bolt them

Label Table	
Variant	Label Text
COAX	COAX
STP	STP

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TIDA-00223		Designed for: Public Release		Mod. Date: 7/10/2014	
Project Title: FPD-Link III Class-D Amplifier		Sheet Title: Hardware		Sheet: 7 of 7	
Number: SAT0084		Rev: E1.1		File: SAT0084E1-1 Hardware.SchDoc	
Drawn By: Viktor Schneigelberger		Engineer: Viktor Schneigelberger		Contact: http://www.ti.com/support	



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